



**Toshiba gate driver photocoupler with 2.5A peak output current in low profile package**

*Ultra slim device guarantees 5kV isolation and 8.0mm creepage and clearance distances*

**Düsseldorf, Germany, 19 April 2018** – Toshiba Electronics Europe today announced the launch of a new gate driver photocoupler housed in a low-profile SO8L package. The TLP5832 delivers 2.5A peak output current ( $I_{OPH}, I_{OPL}$ ) and can directly drive medium-class IGBTs and MOSFETs in applications such as inverters for industrial, air conditioning and solar applications as well as servo amplifiers.

Adoption of the SO8L package delivers a device, that is just 2.3mm high - approximately 54% lower than Toshiba's current products that are available in SDIP6 and DIP8 packages. The SO8L package provides support for modern applications where there is often limited mounting height and limited space.

In spite of its small size, the IC offers an isolation voltage ( $BV_S$ ) of 5000V<sub>rms</sub> and guarantees creepage and clearance distances of minimum 8.0mm, making it suitable for applications requiring high insulation performance, including safety-critical designs.

Additionally, the new TLP5832 guarantees the propagation delay time ( $t_{PLH}$ ,  $t_{PHL}$ ) to be 200ns and the propagation delay skew ( $t_{PSK}$ ) to be  $\pm 80$ ns right across the full operating temperature range of  $-40^{\circ}\text{C}$  to  $+110^{\circ}\text{C}$ . As a result, high-efficiency inverter circuits can be designed by reducing temperature-related design margins.

Shipments has started.

###

**About Toshiba Electronics Europe**

[Toshiba Electronics Europe GmbH](#) (TEE) is the European electronic components business of [Toshiba Electronic Devices and Storage Corporation](#). TEE offers European consumers and businesses a wide variety of innovative hard disk drive (HDD) products plus semiconductor solutions for automotive, industrial, IoT, motion control, telecoms, networking, consumer and white goods applications. The company's broad portfolio encompasses integrated wireless ICs, power semiconductors, microcontrollers, optical semiconductors, ASICs, ASSPs and discrete devices ranging from diodes to logic ICs.

Formed in 1973 in Neuss, Germany, TEE has headquarters in Düsseldorf, Germany, with branch offices in Germany, France, Italy, Spain, Sweden and the United Kingdom providing design, manufacturing, marketing and sales. Company president is Mr. Akira Morinaga.

For more company information visit TEE's web site at [www.toshiba.semicon-storage.com](http://www.toshiba.semicon-storage.com).

**Contact details for publication:**

Toshiba Electronics Europe GmbH, Hansaallee 181, D-40549 Düsseldorf, Germany

Tel: +49 (0) 211 5296 0 Fax: +49 (0) 211 5296 79197

Web: [www.toshiba.semicon-storage.com/eu/company/news.html](http://www.toshiba.semicon-storage.com/eu/company/news.html)

E-mail: [discrete-ic@toshiba-components.com](mailto:discrete-ic@toshiba-components.com)

**Contact details for editorial enquiries:**

Michelle Shrimpton, Toshiba Electronics Europe GmbH

Tel: +44 (0)193 282 2832

E-mail: [MShrimpton@teu.toshiba.de](mailto:MShrimpton@teu.toshiba.de)

**Issued by:**

Birgit Schöniger, Publitek

Tel: +44 (0) 20 8429 6554

Web: [www.publitek.com](http://www.publitek.com)

E-mail: [birgit.schoeniger@publitek.com](mailto:birgit.schoeniger@publitek.com)

April 2018

Ref. 7118/A